

# NTMD6N04R2

## Power MOSFET

### 40 V, 5.8 A, Dual N-Channel SOIC-8

#### Features

- Designed for use in low voltage, high speed switching applications
- Ultra Low On-Resistance Provides Higher Efficiency and Extends Battery Life
  - $R_{DS(on)} = 0.027 \Omega$ ,  $V_{GS} = 10 \text{ V}$  (Typ)
  - $R_{DS(on)} = 0.034 \Omega$ ,  $V_{GS} = 4.5 \text{ V}$  (Typ)
- Miniature SOIC-8 Surface Mount Package Saves Board Space
- Diode is Characterized for Use in Bridge Circuits
- Diode Exhibits High Speed, with Soft Recovery
- Pb-Free Package is Available

#### Applications

- DC-DC Converters
- Computers
- Printers
- Cellular and Cordless Phones
- Disk Drives and Tape Drives

#### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	40	V
Gate-to-Source Voltage - Continuous	$V_{GS}$	$\pm 20$	V
Drain Current (Note 1)			
- Continuous @ $T_A = 25^\circ\text{C}$	$I_D$	5.8	Adc
- Single Pulse ( $t_p \leq 10 \mu\text{s}$ )	$I_{DM}$	29	Apk
Drain Current (Note 2)			
- Continuous @ $T_A = 25^\circ\text{C}$	$I_D$	4.6	Adc
Total Power Dissipation			
@ $T_A = 25^\circ\text{C}$ (Note 1)	$P_D$	2.0	W
@ $T_A = 25^\circ\text{C}$ (Note 2)		1.29	
Operating and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$
Single Pulse Drain-to-Source Avalanche Energy - Starting $T_J = 25^\circ\text{C}$ ( $V_{DD} = 40 \text{ Vdc}$ , $V_{GS} = 5.0 \text{ Vdc}$ , $V_{dc}$ , Peak $I_L = 7.0 \text{ Apk}$ , $L = 10 \text{ mH}$ , $R_G = 25 \Omega$ )	$E_{AS}$	245	mJ
Thermal Resistance			
- Junction-to-Ambient (Note 1)	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$
- Junction-to-Ambient (Note 2)		97	
Maximum Lead Temperature for Soldering Purposes for 10 Sec	$T_L$	260	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. When surface mounted to an FR4 board using 1" pad size,  $t \leq 10 \text{ s}$
2. When surface mounted to an FR4 board using 1" pad size,  $t = \text{steady state}$

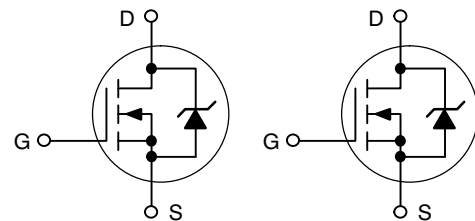


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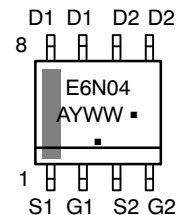
<http://onsemi.com>

$V_{DSS}$	$R_{DS(on)}$ Typ	$I_D$ Max
40 V	27 m $\Omega$ @ $V_{GS} = 10 \text{ V}$	5.8 A

#### N-Channel



#### MARKING DIAGRAM & PIN ASSIGNMENT



E6N04 = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 WW = Work Week  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

Device	Package	Shipping†
NTMD6N04R2G	SOIC-8 (Pb-Free)	2500/Tape & Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# NTMD6N04R2

## ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage (V <sub>GS</sub> = 0 Vdc, I <sub>D</sub> = 250 μA) Temperature Coefficient (Positive)	$V_{(BR)DSS}$ $V_{(BR)DSS}/T_J$	40 -	47 45	- -	Vdc mV/°C
Zero Gate Voltage Drain Current (V <sub>DS</sub> = 40 Vdc, V <sub>GS</sub> = 0 Vdc, T <sub>J</sub> = 25°C) (V <sub>DS</sub> = 40 Vdc, V <sub>GS</sub> = 0 Vdc, T <sub>J</sub> = 125°C)	I <sub>DSS</sub>	- -	- -	1.0 10	μAdc
Gate-Body Leakage Current (V <sub>GS</sub> = ±20 Vdc, V <sub>DS</sub> = 0 Vdc)	I <sub>GSS</sub>	-	-	± 100	nAdc

### ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage (V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μAdc) Temperature Coefficient (Negative)	$V_{GS(th)}$ $V_{GS(th)}/T_J$	1.0 -	1.9 4.7	3.0 -	Vdc mV/°C
Static Drain-to-Source On-State Resistance (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 5.8 Adc) (V <sub>GS</sub> = 4.5 Vdc, I <sub>D</sub> = 3.9 Adc)	R <sub>DS(on)</sub>	- -	0.027 0.034	0.034 0.043	Ω
Forward Transconductance (V <sub>DS</sub> = 10 Vdc, I <sub>D</sub> = 5.8 Adc)	g <sub>FS</sub>	-	8.12	-	Mhos

### DYNAMIC CHARACTERISTICS

Input Capacitance	(V <sub>DS</sub> = 32 Vdc, V <sub>GS</sub> = 0 Vdc, f = 1.0 MHz)	C <sub>iss</sub>	-	723	900	pF
Output Capacitance		C <sub>oss</sub>	-	156	225	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	53	75	

### SWITCHING CHARACTERISTICS (Notes 3 & 4)

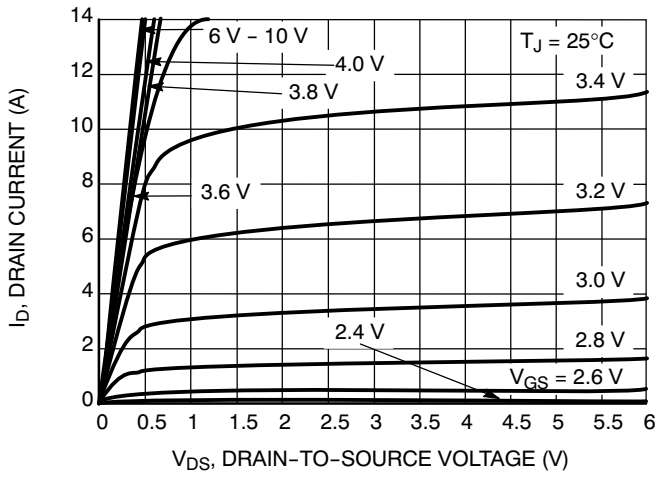
Turn-On Delay Time	(V <sub>DD</sub> = 20 Vdc, I <sub>D</sub> = 5.8 A, V <sub>GS</sub> = 10 V, R <sub>G</sub> = 6 Ω)	t <sub>d(on)</sub>	-	10	18	ns
Rise Time		t <sub>r</sub>	-	20	35	
Turn-Off Delay Time		t <sub>d(off)</sub>	-	45	70	
Fall Time		t <sub>f</sub>	-	40	65	
Turn-On Delay Time	(V <sub>DD</sub> = 20 Vdc, I <sub>D</sub> = 5.8 A, V <sub>GS</sub> = 4.5 V, R <sub>G</sub> = 6 Ω)	t <sub>d(on)</sub>	-	15	-	ns
Rise Time		t <sub>r</sub>	-	55	-	
Turn-Off Delay Time		t <sub>d(off)</sub>	-	30	-	
Fall Time		t <sub>f</sub>	-	35	-	
Gate Charge	(V <sub>DS</sub> = 20 Vdc, V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 5.8 A)	Q <sub>T</sub>	-	20	30	nC
		Q <sub>gs</sub>	-	2.5	-	
		Q <sub>gd</sub>	-	5.5	-	

### BODY-DRAIN DIODE RATINGS (Note 3)

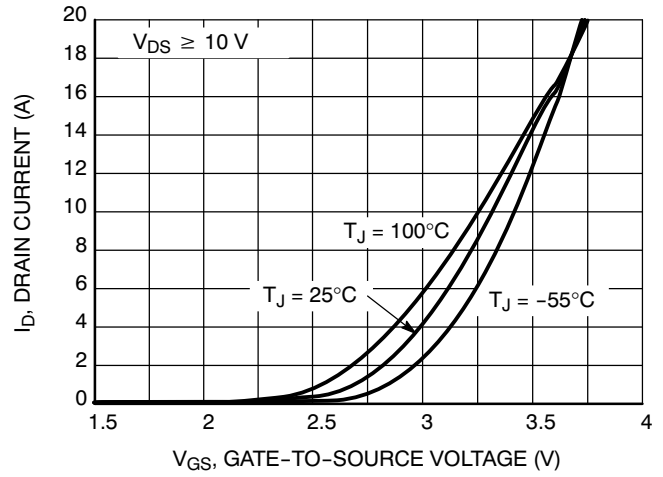
Diode Forward On-Voltage	(I <sub>S</sub> = 1.7 Adc, V <sub>GS</sub> = 0 V) (I <sub>S</sub> = 1.7 Adc, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150°C)	V <sub>SD</sub>	- -	0.76 0.56	1.1 -	Vdc
Reverse Recovery Time	(I <sub>S</sub> = 1.7 A, V <sub>GS</sub> = 0 V, di <sub>S</sub> /dt = 100 A/μs)	t <sub>rr</sub>	-	23	-	ns
		t <sub>a</sub>	-	16	-	
		t <sub>b</sub>	-	7	-	
Reverse Recovery Stored Charge (I <sub>S</sub> = 1.7 A, di <sub>S</sub> /dt = 100 A/μs, V <sub>GS</sub> = 0 V)		Q <sub>RR</sub>	-	20	-	nC

3. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
4. Switching characteristics are independent of operating junction temperature.

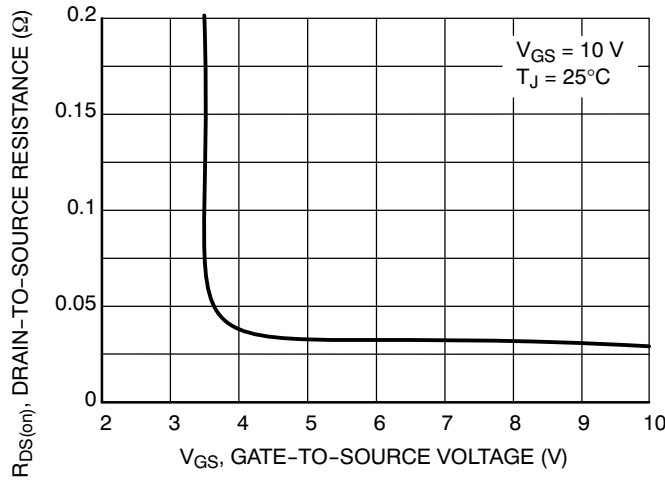
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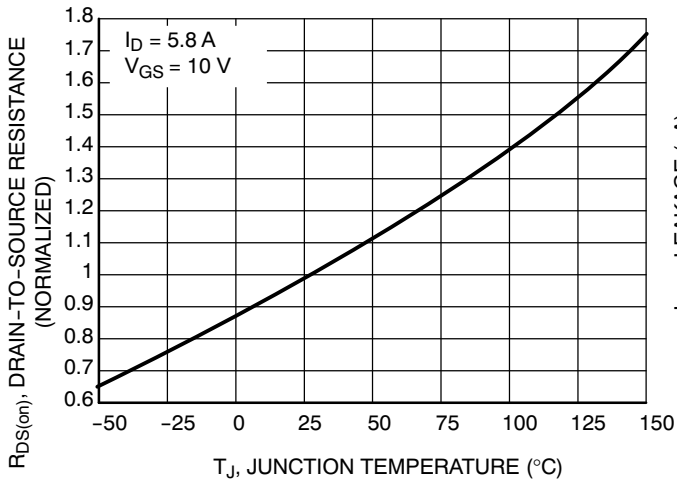
**Figure 1. On-Region Characteristics**



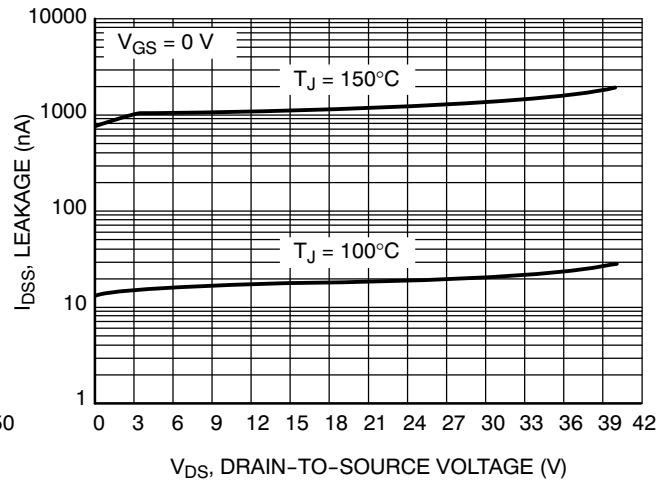
**Figure 2. Transfer Characteristics**



**Figure 3. On-Resistance vs. Gate-to-Source Voltage**

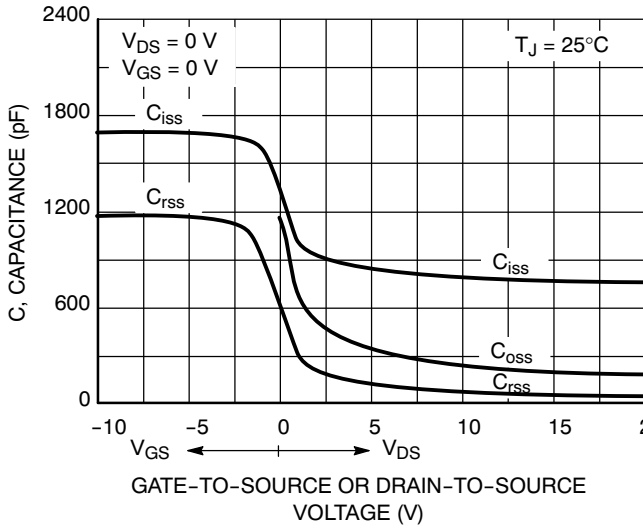


**Figure 4. On Resistance Variation with Temperature**

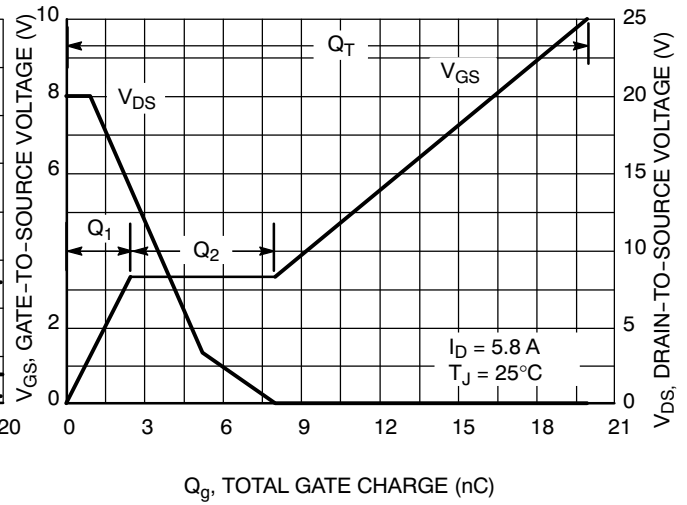


**Figure 5. Drain-to-Source Leakage Current vs. Voltage**

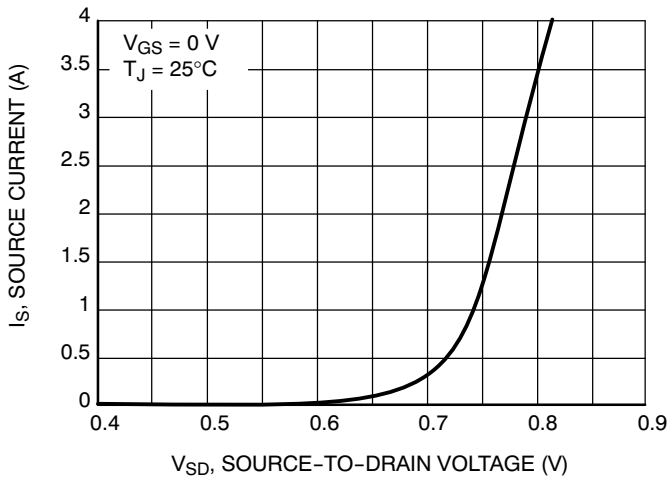
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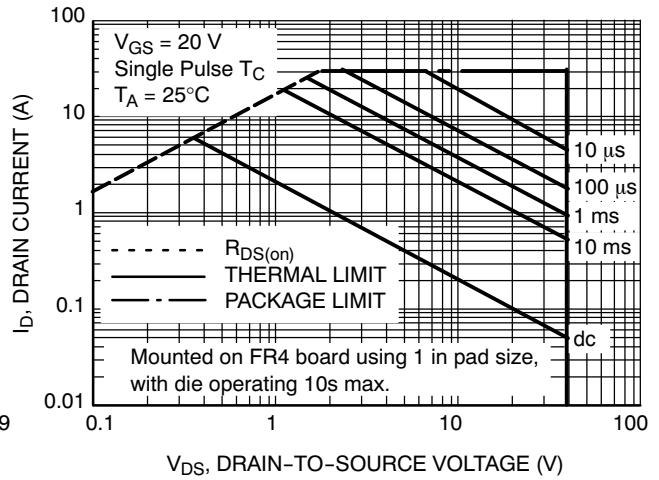
**Figure 6. Capacitance Variation**



**Figure 7. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge**



**Figure 8. Diode Forward Voltage vs. Current**

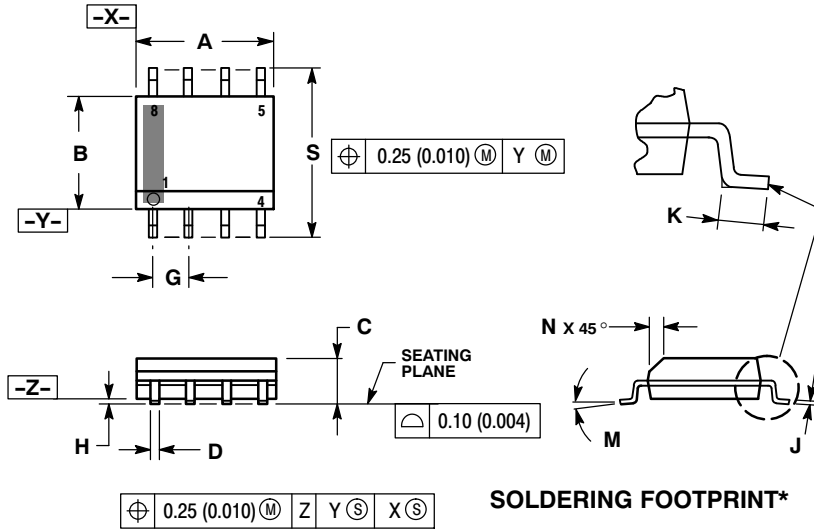


**Figure 9. Maximum Rated Forward Biased Safe Operating Area**

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## PACKAGE DIMENSIONS

SOIC-8 NB  
CASE 751-07  
ISSUE AJ

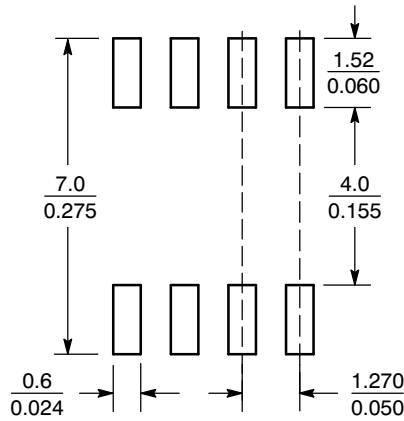


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

**SOLDERING FOOTPRINT\***



SCALE 6:1 (mm/inches)

**STYLE 11:**

- PIN 1. SOURCE 1
- 2. GATE 1
- 3. SOURCE 2
- 4. GATE 2
- 5. DRAIN 2
- 6. DRAIN 2
- 7. DRAIN 1
- 8. DRAIN 1

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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